Build Up HDI (Standard)

HDI12_3+6(8b)+3_1,55_35_engl

12 - Layers

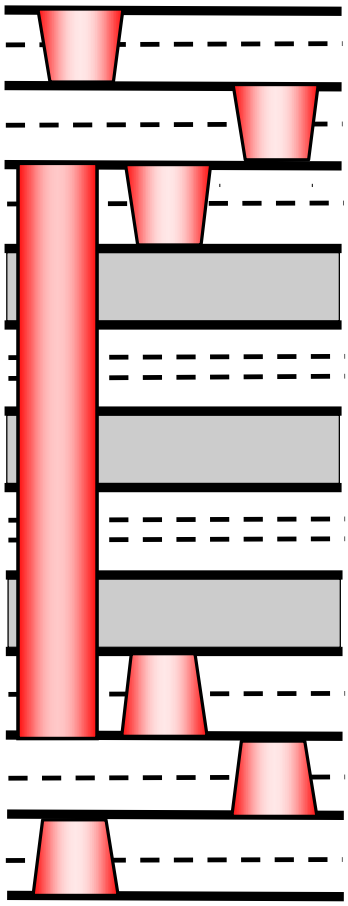
Core: 0,20 mm Cu 35/35 µm

WE-Articel No.: | **3 + 6(8B) + 3**

Customer:

WÜRTH ELEKTRONIK

only CBT Schopfheim



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		30	
					1 x 1080	60	
	3		Foil	9 µm		30	
					1 x 1080	60	
	4			35 µm		33	
			0,200 mm			200	
	5			35 µm		33	
					2 x 1080	124	
	6			35 µm		33	
			0,200 mm			200	
	7			35 µm		33	
					2 x 1080	124	
	8			35 µm		33	
			0,200 mm			200	
	9			35 µm		33	
					1 x 1080	60	
	10		Foil	9 µm		30	
					1 x 1080	60	
	11		Foil	12 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1550

Note: Lamination thickness for Prepregs depending on layout characteristics.

							Date:	Engineer:
final lamination thickness:	**1,55**	+/-	0,13	mm				
thickness with electro plated Cu:	1,64	+/-	0,16	mm				
total thickness with soldermask	1,70	+/-	0,18	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	
29.03.2006	**S. Keller**	04.05.2006	M.Kress	04.05.2006	R.Schönholz	00	page: 19+